

Electronic Patent Application Fee Transmittal

Application Number:	10685312			
Filing Date:	14-Oct-2003			
Title of Invention:	INTERPOSER SUBSTRATES WITH MULTI-SEGMENT INTERCONNECT SLOTS, SEMICONDUCTOR DIE PACKAGES INCLUDING SAME, SEMICONDUCTOR DICE FOR USE THEREWITH AND METHODS OF FABRICATION			
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Filer:	Joseph A. Walkowski/Debra Mitchell			
Attorney Docket Number:	2269-5520.1US (02-0676.01			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Request for continued examination	1801	1	810	810
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